

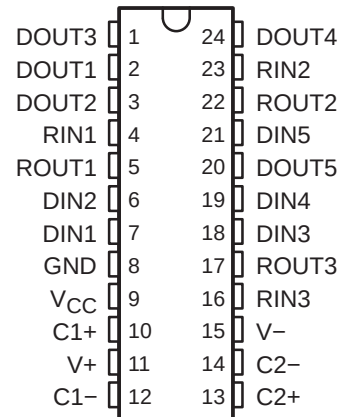
MAX207

5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER WITH ± 15 -kV ESD PROTECTION

SLLS592B – OCTOBER 2003 – REVISED JANUARY 2004

- ESD Protection for RS-232 I/O Pins
 - ± 15 kV – Human-Body Model
- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates at 5-V V_{CC} Supply
- Operates Up To 120 kbit/s
- External Capacitors . . . $4 \times 0.1 \mu\text{F}$
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- Applications
 - Battery-Powered Systems, PDAs, Notebooks, Laptops, Palmtop PCs, and Hand-Held Equipment

DB OR DW PACKAGE
(TOP VIEW)



description/ordering information

The MAX207 consists of five line drivers, three line receivers, and a dual charge-pump circuit with ± 15 -kV ESD protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 5-V supply. The devices operate at data signaling rates up to 120 kbit/s and a maximum of 30-V/ μs driver output slew rate.

ORDERING INFORMATION

T_A	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	SOIC (DW)	Tube of 25	MAX207CDW	MAX207C
		Reel of 2000	MAX207CDWR	
	SSOP (DB)	Reel of 2000	MAX207CDBR	MA207C
-40°C to 85°C	SOIC (DW)	Tube of 25	MAX207IDW	MAX207I
		Reel of 2000	MAX207IDWR	
	SSOP (DB)	Reel of 2000	MAX207IDBR	MB207I

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2004, Texas Instruments Incorporated

MAX207
5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER
WITH ± 15 -kV ESD PROTECTION

SLLS592B – OCTOBER 2003 – REVISED JANUARY 2004

Function Tables

EACH DRIVER

INPUT D _{IN}	OUTPUT D _{OUT}
L	H
H	L

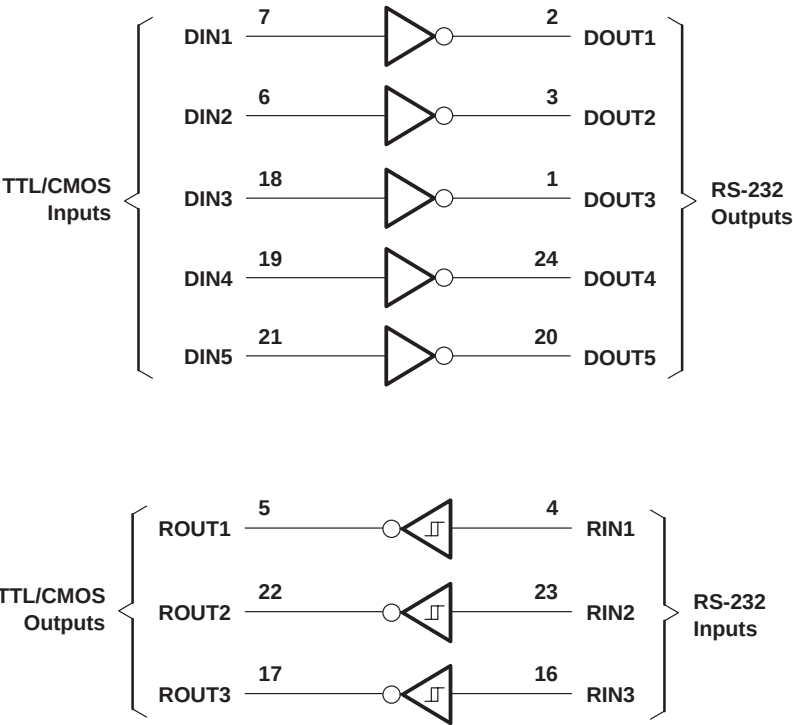
H = high level, L = low level

EACH RECEIVER

INPUT R _{IN}	OUTPUT R _{OUT}
L	H
H	L
Open	H

H = high level, L = low level, Open = input disconnected or connected driver off

logic diagram (positive logic)



MAX207

5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER

WITH ± 15 -kV ESD PROTECTION

SLLS592B – OCTOBER 2003 – REVISED JANUARY 2004

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} (see Note 1)	–0.3 V to 6 V
Positive charge pump voltage range, $V+$ (see Note 1)	$V_{CC} - 0.3$ V to 14 V
Negative charge pump voltage range, $V-$ (see Note 1)	–14 V to 0.3 V
Input voltage range, V_I : Drivers	–0.3 V to $V+ + 0.3$ V
Receivers	± 30 V
Output voltage range, V_O : Drivers	$V- - 0.3$ V to $V+ + 0.3$ V
Receivers	–0.3 V to $V_{CC} + 0.3$ V
Short-circuit duration: D_{OUT}	Continuous
Package thermal impedance, θ_{JA} (see Notes 2 and 3): DB package	63°C/W
DW package	46°C/W
Operating virtual junction temperature, T_J	150°C
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages are with respect to network GND.
2. Maximum power dissipation is a function of $T_J(\text{max})$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4 and Figure 4)

			MIN	NOM	MAX	UNIT
	Supply voltage		4.5	5	5.5	V
V_{IH}	Driver high-level input voltage	D_{IN}	2			V
V_{IL}	Driver low-level input voltage	D_{IN}			0.8	V
V_I	Driver input voltage	D_{IN}	0		5.5	V
	Receiver input voltage		–30		30	
T_A	Operating free-air temperature	MAX207C	0		70	°C
		MAX207I	–40		85	

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at $V_{CC} = 5$ V $\pm$ 0.5 V.

electrical characteristics over recommended ranges of supply voltage (unless otherwise noted) (see Note 4 and Figure 4)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{CC} Supply current	No load, $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$		11	20	mA

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at $V_{CC} = 5$ V $\pm$ 0.5 V.



DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 4)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{OH} High-level output voltage	D _{OUT} at R _L = 3 k Ω to GND, D _{IN} = GND	5	9		V
V _{OL} Low-level output voltage	D _{OUT} at R _L = 3 k Ω to GND, D _{IN} = V _{CC}	-5	-9		V
I _{IH} High-level input current	V _I = V _{CC}		15	200	μ A
I _{IL} Low-level input current	V _I at 0 V		-15	-200	μ A
I _{OS} [‡] Short-circuit output current	V _{CC} = 5.5 V, V _O = 0 V		± 10	± 60	mA
r _O Output resistance	V _{CC} , V ₊ , and V ₋ = 0 V, V _O = ± 2 V	300			Ω

[†] All typical values are at V_{CC} = 5 V, and T_A = 25°C.

[‡] Short-circuit durations should be controlled to prevent exceeding the device absolute power-dissipation ratings, and not more than one output should be shorted at a time.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 5 V $\pm$ 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 4)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
Maximum data rate	C _L = 50 to 1000 pF, R _L = 3 k Ω to 7 k Ω , One D _{OUT} switching, See Figure 1	120			kbit/s
t _{PLH} (D) Propagation delay time, low- to high-level output	C _L = 2500 pF, R _L = 3 k Ω , all drivers loaded, See Figure 1		2		μ s
t _{PHL} (D) Propagation delay time, high- to low-level output	C _L = 2500 pF, R _L = 3 k Ω , all drivers loaded, See Figure 1		2		μ s
t _{sk} (p) Pulse skew [§]	C _L = 150 pF to 2500 pF, R _L = 3 k Ω to 7 k Ω , See Figure 2		300		ns
SR(tr) Slew rate, transition region (see Figure 1)	C _L = 50 pF to 1000 pF, R _L = 3 k Ω to 7 k Ω , V _{CC} = 5 V	3	6	30	V/ μ s

[†] All typical values are at V_{CC} = 5 V, and T_A = 25°C.

[§] Pulse skew is defined as |t_{PLH} – t_{PHL}| of each channel of the same device.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 5 V $\pm$ 0.5 V.

ESD protection

PIN	TEST CONDITIONS	TYP	UNIT
D _{OUT} , R _{IN}	Human-Body Model	± 15	kV

MAX207

5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER

WITH ± 15 -kV ESD PROTECTION

SLLS592B – OCTOBER 2003 – REVISED JANUARY 2004

RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 4)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{OH} High-level output voltage	I _{OH} = -1 mA	3.5	V _{CC} - 0.4 V		V
V _{OL} Low-level output voltage	I _{OL} = 1.6 mA			0.4	V
V _{IT+} Positive-going input threshold voltage	V _{CC} = 5 V, T _A = 25°C		1.7	2.4	V
V _{IT-} Negative-going input threshold voltage	V _{CC} = 5 V, T _A = 25°C	0.8	1.2		V
V _{hys} Input hysteresis (V _{IT+} - V _{IT-})		0.2	0.5	1	V
r _i Input resistance	V _I = ± 3 V to ± 25 V	3	5	7	k Ω

[†] All typical values are at V_{CC} = 5 V, and T_A = 25°C.

NOTE 4: Test conditions are C1-C4 = 0.1 μ F at V_{CC} = 5 V $\pm$ 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 3)

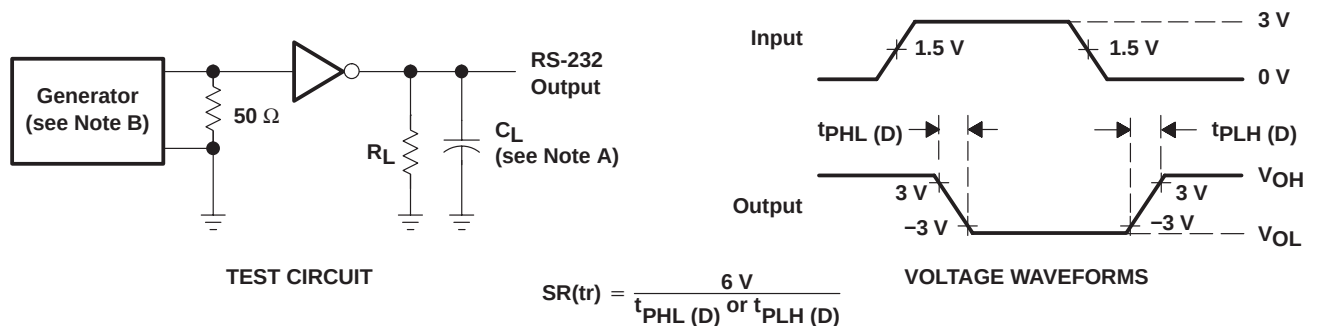
PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
t _{PLH} Propagation delay time, low- to high-level output	C _L = 150 pF		0.5	10	μ s
t _{PHL} Propagation delay time, high- to low-level output			0.5	10	μ s
t _{sk(p)} Pulse skew [‡]			300		ns

[†] All typical values are at V_{CC} = 5 V, and T_A = 25°C.

[‡] Pulse skew is defined as |t_{PLH} - t_{PHL}| of each channel of the same device.

NOTE 4: Test conditions are C1-C4 = 0.1 μ F, at V_{CC} = 5 V $\pm$ 0.5 V.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 120 kbit/s, Z_O = 50 Ω , 50% duty cycle, t_r $\leq$ 10 ns, t_f $\leq$ 10 ns.

Figure 1. Driver Slew Rate

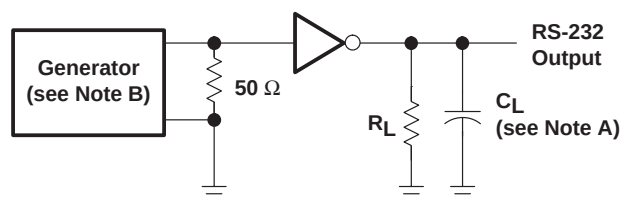
MAX207

5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER

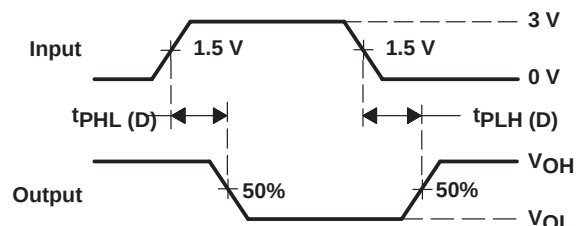
WITH ± 15 -kV ESD PROTECTION

SLLS592B – OCTOBER 2003 – REVISED JANUARY 2004

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT

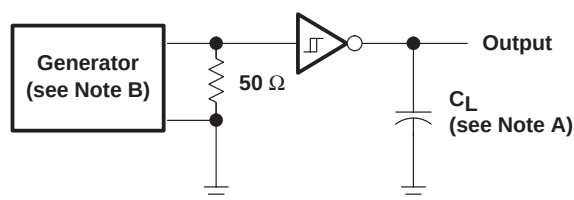


VOLTAGE WAVEFORMS

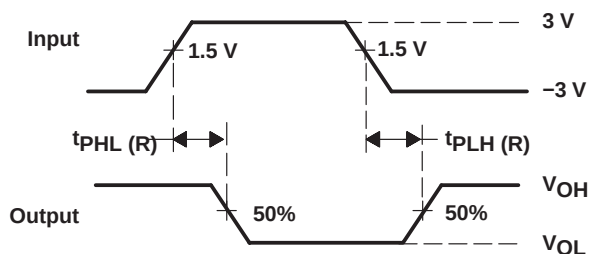
NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 120 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10$ ns, $t_f \leq 10$ ns.

Figure 2. Driver Pulse Skew



TEST CIRCUIT



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10$ ns, $t_f \leq 10$ ns.

Figure 3. Receiver Propagation Delay Times

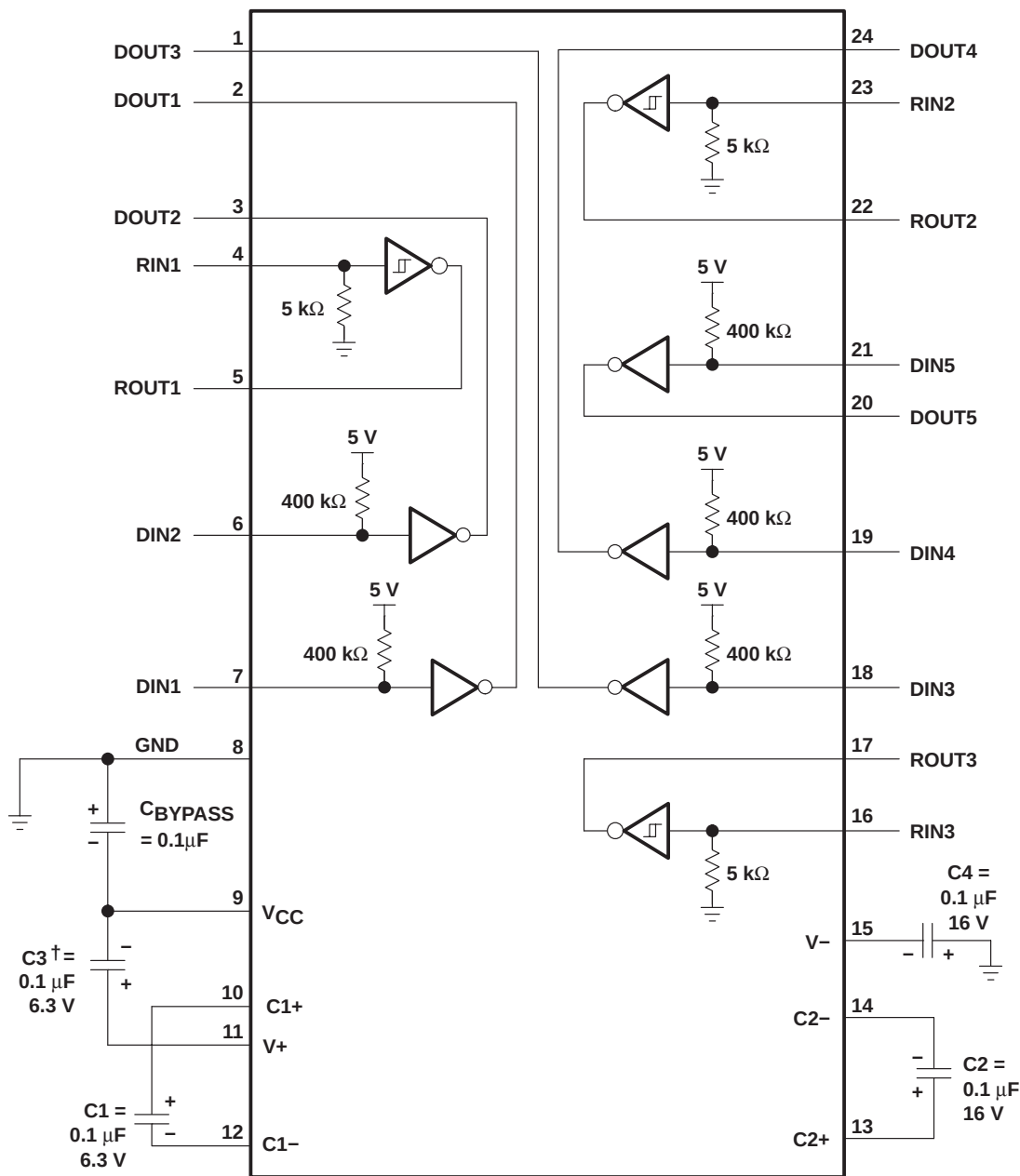
MAX207

5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER

WITH ± 15 -kV ESD PROTECTION

SLLS592B – OCTOBER 2003 – REVISED JANUARY 2004

APPLICATION INFORMATION



† C3 can be connected to V_{CC} or GND.

NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

Figure 4. Typical Operating Circuit and Capacitor Values

MAX207

5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER

WITH ± 15 -kV ESD PROTECTION

SLLS592B – OCTOBER 2003 – REVISED JANUARY 2004

APPLICATION INFORMATION

capacitor selection

The capacitor type used for C1–C4 is not critical for proper operation. The MAX207 requires 0.1- μ F capacitors, although capacitors up to 10 μ F can be used without harm. Ceramic dielectrics are suggested for the 0.1- μ F capacitors. When using the minimum recommended capacitor values, make sure the capacitance value does not degrade excessively as the operating temperature varies. If in doubt, use capacitors with a larger (e.g., 2 $\times$) nominal value. The capacitors' effective series resistance (ESR), which usually rises at low temperatures, influences the amount of ripple on V+ and V–.

Use larger capacitors (up to 10 μ F) to reduce the output impedance at V+ and V–.

Bypass V_{CC} to ground with at least 0.1 μ F. In applications sensitive to power-supply noise generated by the charge pumps, decouple V_{CC} to ground with a capacitor the same size as (or larger than) the charge-pump capacitors (C1–C4).

ESD protection

TI MAX207 devices have standard ESD protection structures incorporated on the pins to protect against electrostatic discharges encountered during assembly and handling. In addition, the RS232 bus pins (driver outputs and receiver inputs) of these devices have an extra level of ESD protection. Advanced ESD structures were designed to successfully protect these bus pins against ESD discharge of ± 15 -kV when powered down.

ESD test conditions

ESD testing is stringently performed by TI, based on various conditions and procedures. Please contact TI for a reliability report that documents test setup, methodology, and results.

Human-Body Model

The Human-Body Model (HBM) of ESD testing is shown in Figure 5, while Figure 6 shows the current waveform that is generated during a discharge into a low impedance. The model consists of a 100-pF capacitor, charged to the ESD voltage of concern, and subsequently discharged into the device under test (DUT) through a 1.5-k Ω resistor.

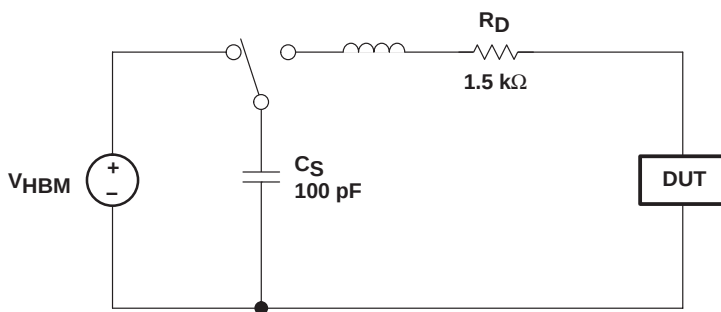


Figure 5. HBM ESD Test Circuit

APPLICATION INFORMATION

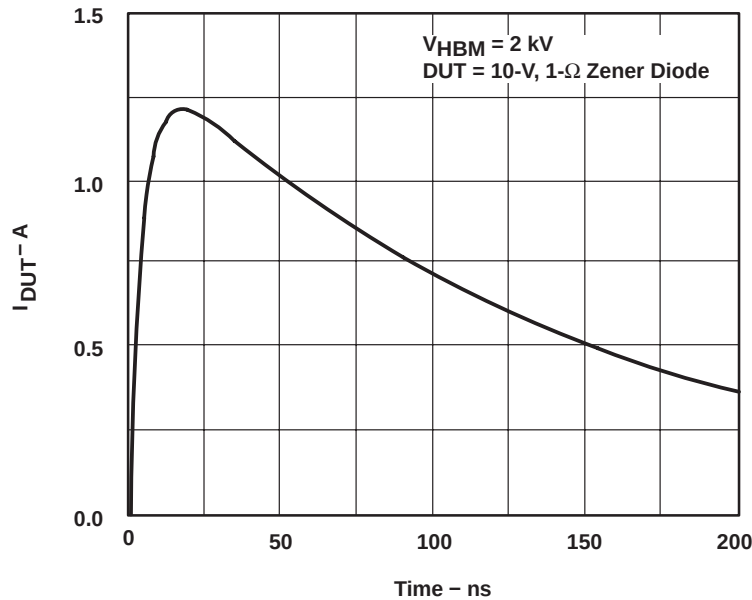


Figure 6. Typical HBM Current Waveform

Machine Model

The Machine Model (MM) ESD test applies to all pins using a 200-pF capacitor with no discharge resistance. The purpose of the MM test is to simulate possible ESD conditions that can occur during the handling and assembly processes of manufacturing. In this case, ESD protection is required for all pins, not just RS-232 pins. However, after PC board assembly, the MM test no longer is as pertinent to the RS-232 pins.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
MAX207CDB	Obsolete	Production	SSOP (DB) 24	-	-	Call TI	Call TI	0 to 70	MA207C
MAX207CDBR	Active	Production	SSOP (DB) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MA207C
MAX207CDBR.A	Active	Production	SSOP (DB) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MA207C
MAX207CDW	Obsolete	Production	SOIC (DW) 24	-	-	Call TI	Call TI	0 to 70	MAX207C
MAX207CDWR	Obsolete	Production	SOIC (DW) 24	-	-	Call TI	Call TI	0 to 70	MAX207C
MAX207IDBR	Active	Production	SSOP (DB) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MB207I
MAX207IDBR.A	Active	Production	SSOP (DB) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MB207I
MAX207IDW	Obsolete	Production	SOIC (DW) 24	-	-	Call TI	Call TI	-40 to 85	MAX207I
MAX207IDWR	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX207I
MAX207IDWR.A	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX207I

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

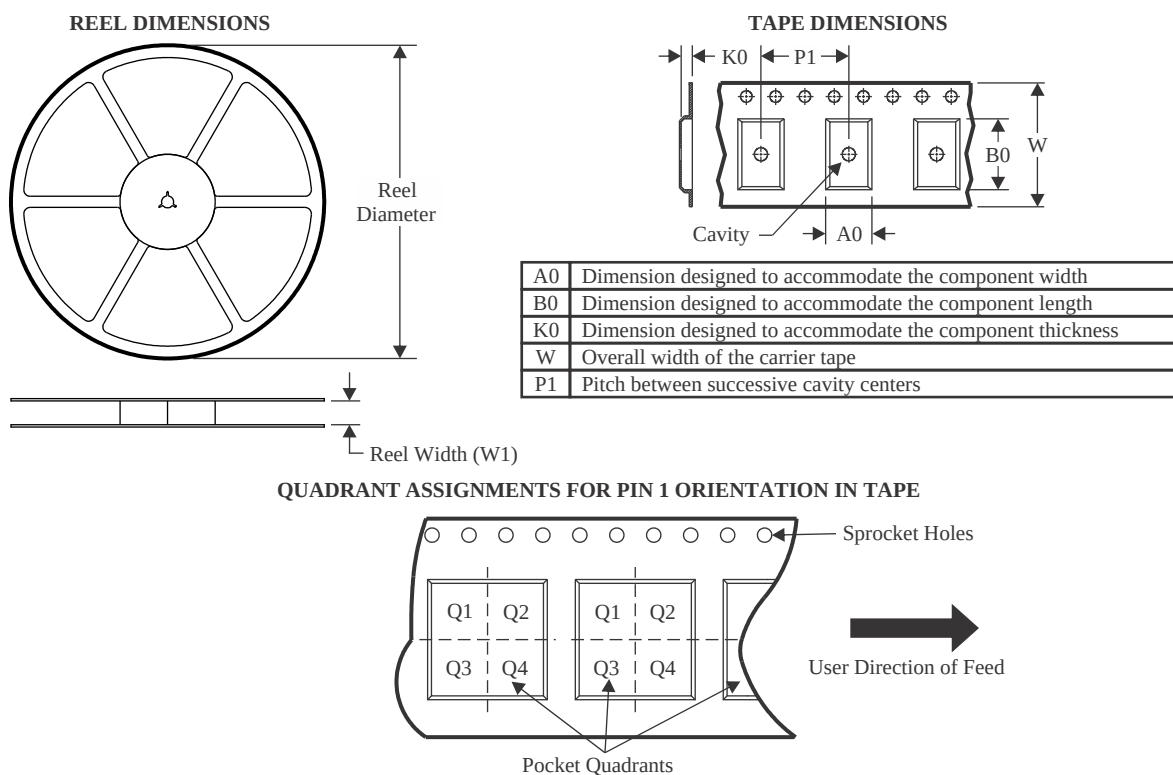
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative

and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

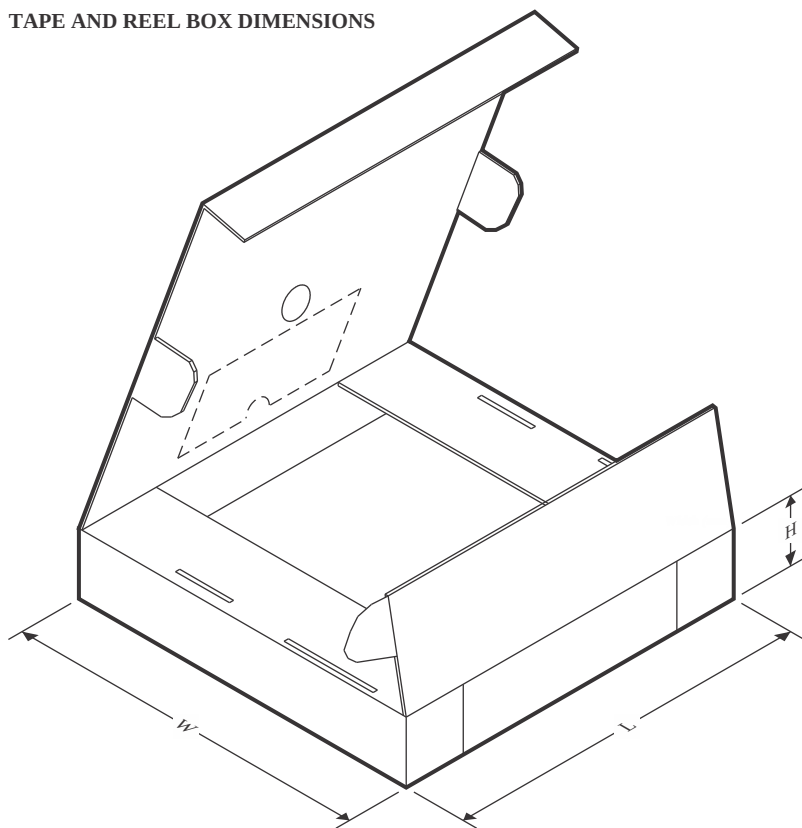
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MAX207CDBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
MAX207IDBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
MAX207IDWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS

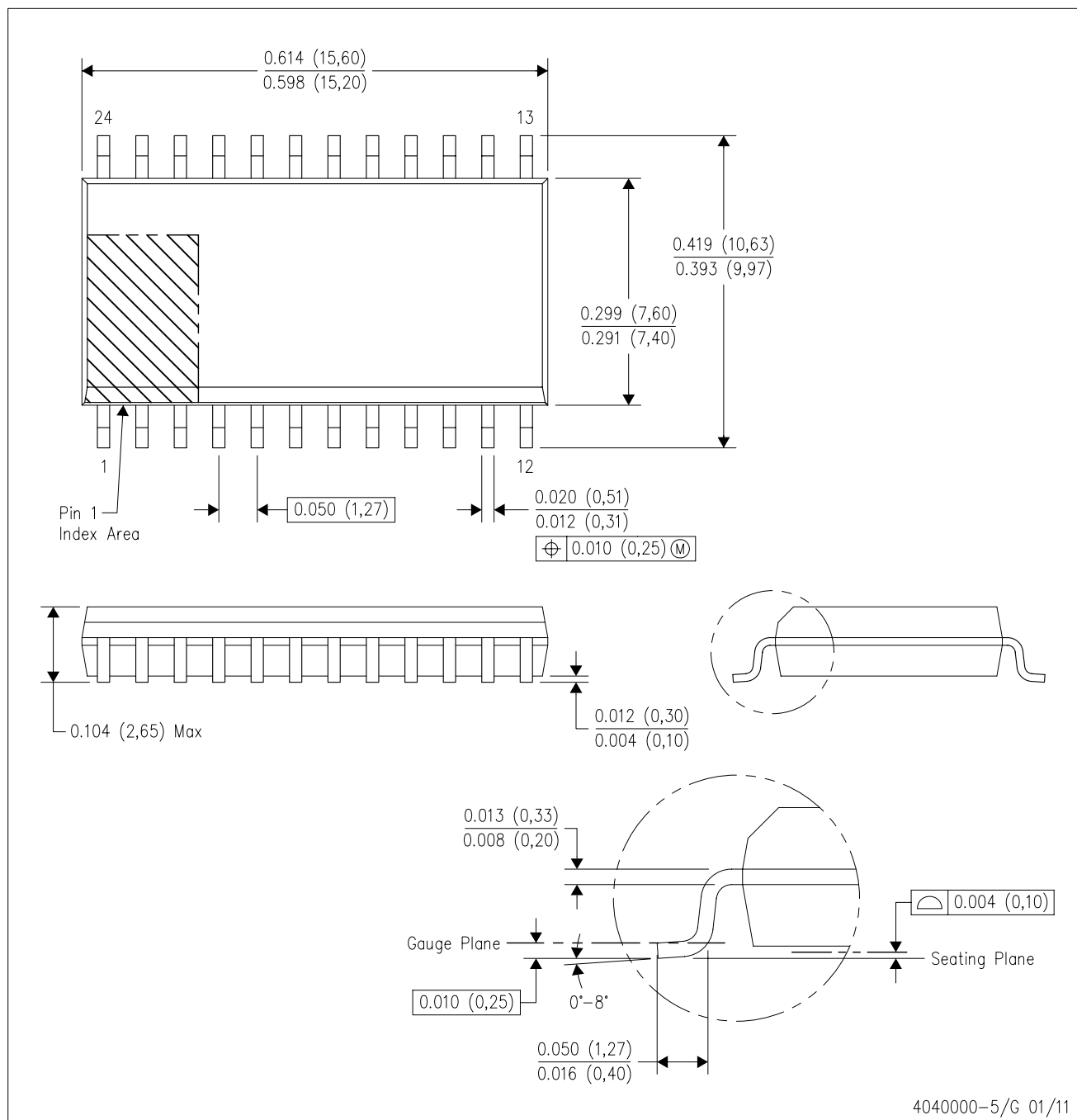


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MAX207CDBR	SSOP	DB	24	2000	353.0	353.0	32.0
MAX207IDBR	SSOP	DB	24	2000	353.0	353.0	32.0
MAX207IDWR	SOIC	DW	24	2000	350.0	350.0	43.0

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE

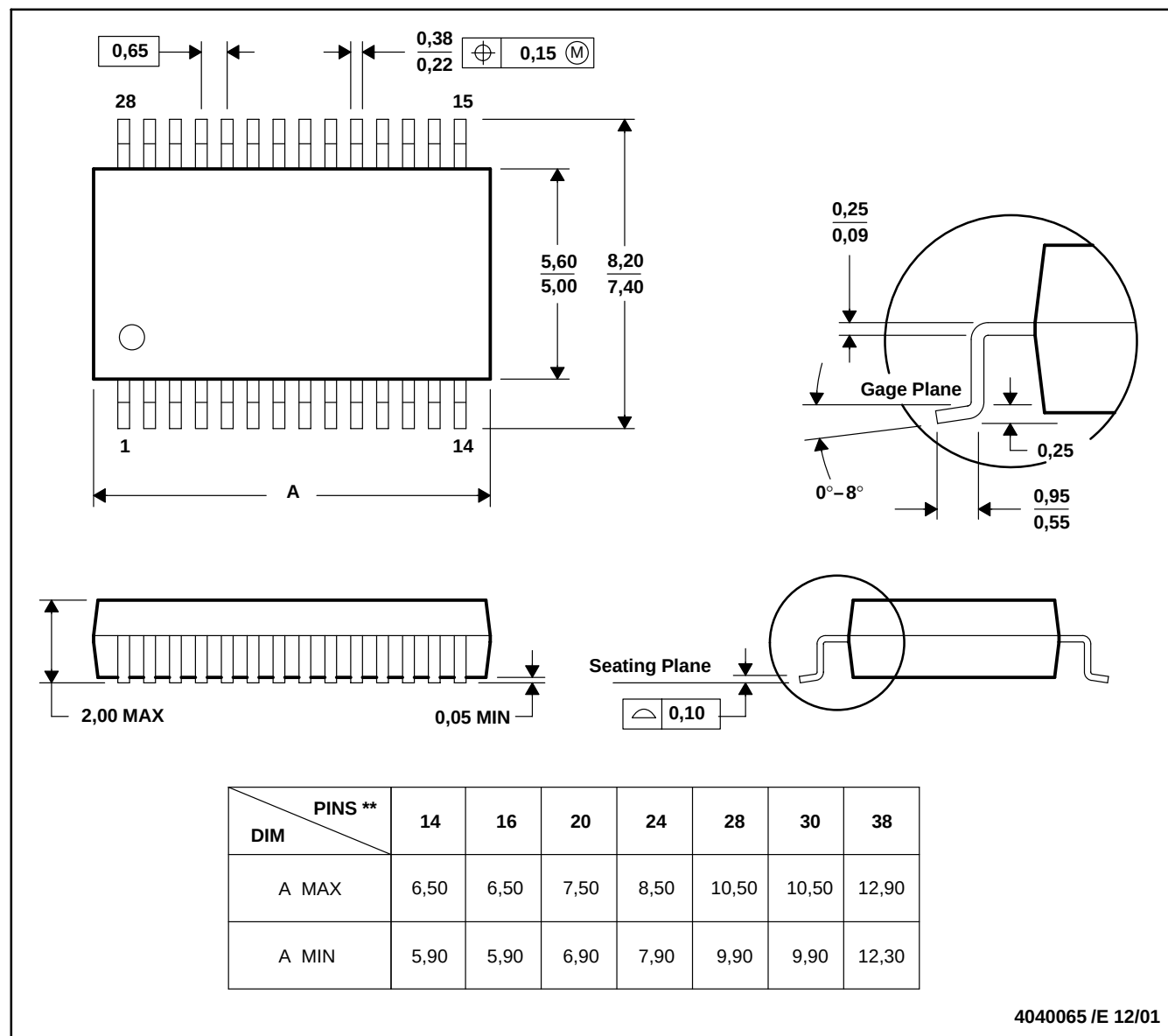


- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AD.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2025, Texas Instruments Incorporated